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25. The method of claim 21, wherein said gas comprised of hydrogen incorporated within a plasma removes residue formed in said opening in said insulating layer.

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REMARKS

Claims 1-20 are pending. Claims 16-20 have been withdrawn from consideration. With this amendment, Applicants propose to cancel claims 1-15 without prejudice so as to expedite prosecution and to add claims 21-25.

Applicants submit a clean copy of the instant specification herewith per the Examiner's request.

With this amendment, Applicants amend the Title so as to be in allowable form.

Newly added claims 21-25 specifically recite a method of forming an electronic device with a via/contact which uses a novel method of cleaning the residue left within the opening formed in the insulating layer prior to the via/contact formation. The method of Nakata specifically utilizes a halogen incorporated into a plasma. The method of the instant invention specifically does not use such gases because of the problems associated with them. See page 5 of the originally filed instant application. In light of this, newly added claims 21-25 are believed to be allowable over the cited references.

Consideration and allowance of claims 21-25 is respectfully requested.

Respectfully submitted,



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